



Material Content Data Sheet



Sales Product Name		TDA21220		Issued		19. July 2018		
MA#		MA001159680						
Package		PG-IQFN-40-1		Weight*		100.11 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.536	1.53	1.53	15343	15343
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		127	
	non noble metal	zinc	7440-66-6	0.051	0.05		510	
	non noble metal	iron	7439-89-6	1.020	1.02		10191	
wire	non noble metal	copper	7440-50-8	41.428	41.37	42.45	413809	424637
	noble metal	gold	7440-57-5	0.308	0.31	0.31	3073	3073
	encapsulation	organic material	carbon black	1333-86-4	0.086	0.09		856
plastics	plastics	epoxy resin	-	4.415	4.41		44100	
	inorganic material	silicondioxide	60676-86-0	38.363	38.32	42.82	383203	428159
	leadfinish	non noble metal	tin	7440-31-5	1.567	1.57	1.57	15657
plating	noble metal	silver	7440-22-4	1.920	1.92	1.92	19181	19181
glue	plastics	epoxy resin	-	0.093	0.09		931	
	noble metal	silver	7440-22-4	0.280	0.28	0.37	2792	3723
	solder	noble metal	silver	7440-22-4	0.036	0.04		355
CLIP plating	non noble metal	tin	7440-31-5	0.028	0.03		284	
	non noble metal	lead	7439-92-1	1.357	1.36	1.43	13555	14194
	noble metal	silver	7440-22-4	0.787	0.79	0.79	7860	7860
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		20	
	non noble metal	zinc	7440-66-6	0.008	0.01		82	
	non noble metal	iron	7439-89-6	0.164	0.16		1636	
	non noble metal	copper	7440-50-8	6.651	6.64	6.81	66435	68173
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com